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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10008700	12/07/2001	438	764	2842	L44

**APPLICANTS: Jeong Hong-Sik; Shin Soo-Ho; Yang Won-Suk; Kim Ki-Nam;
2825

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

REPUBLIC OF KOREA 2000-74315 12/07/2000

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO
Verified and Acknowledged Examiner's initials			5649-905
TITLE : Methods of manufacturing integrated circuit devices having an encapsulated insulation layer U.S. DEPT. OF COMM./PAT. & TM-PTO-436(P-2v 12-94)			

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
		Primary Examiner		
		PREPARED FOR ISSUE		
		Application Examiner		
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